I. <u>AMENDMENTS TO THE CLAIMS</u>

Please cancel claim 8, add new claims 12-15, and enter the claim amendments specified below. A complete listing of all claims in the Application is provided below along with the claim's status, which is indicated in a parenthetical expression after each claim number. For claim amendments, deleted matter is indicated by strike-out text and added matter is indicated by underlined text.

Claims 1-6 (previously canceled)

Claim 7 (currently amended) An electroplating solution for plating tin-bismuth solder coatings comprising:

- a sulfonic acid electrolyte;
- a tin compound soluble in the electrolyte to form a tin sulfonate;
- a bismuth compound soluble in the electrolyte to form a bismuth sulfonate;
- a non-ionic surfactant comprising:
 - (a) a polyethylene glycol-block-polypropylene glycol with a molecular weight between 2,000 and 10,000, and
 - (b) <u>a polyethylene glycol-ran-polypropylene glycol with a molecular</u> weight between 2,000 and 10,000;

a grain refiner; and an antioxidant.

Claim 8 (currently canceled)

Claim 9 (currently amended) The electroplating solution of claim 7 wherein the <u>non-ionic</u> surfactant further pelyethylene glycol-block-polypropylene glycol comprises ethylenediamine tetrakis polyethylene glycol-block-polypropylene glycol tetrol with a molecular weight between 2,000 and 7,000.

Claim 10 (previously amended) The electroplating solution of claim 7 wherein the antioxidant comprises polyhydroxybenzene.

Claim 11 (previously amended) The electroplating solution of claim 7 wherein the grain refiner comprises an acrylic acid.

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Claim 12 (new) The electroplating solution of claim 7 wherein the tin compound comprises a tin sulfonate.

Claim 13 (new) The electroplating solution of claim 7 wherein the bismuth compound comprises a bismuth sulfonate.

Claim 14 (new) The electroplating solution of claim 7 wherein the tin compound comprises a tin sulfonate and the bismuth compound comprises a bismuth sulfonate.

Claim 15 (new) The electroplating solution of claim 7 wherein the sulfonic acid electrolyte comprises a soluble alkane or alkanol sulfonic acid containing 1-5 carbon atoms.

Claim 16 (new) The electroplating solution of claim 7 wherein the sulfonic acid comprises methanesulfonic acid.